

Supplier Name: Texas Instruments Inc. (DUNS# 00-732-1904)
 Contact Info: ti.com/support
 Form/Declaration Type: Distribute - RoHS and IEC 62474 DB
 Created on: 06/12/2022

Details for "TPS7A8301ARGWR"

Current Product Information

TI part number	Lead finish/Ball material	MSL rating/peak reflow	Assembly site	Package Pins	Package body size (mm)	Total device mass (mg)*
TPS7A8301ARGWR	NIPDAU	Level-2-260C-1 YEAR	TI Semiconductor	RGW 20	5x5x0.9	81.8

***Total Device Mass**

The summary mass is a rounded value and will be within approximately +/- 10% of the detailed mass value.

Environmental Ratings Information

RoHS	REACH	Green	IEC 62474 DB
Yes	Yes	Yes	Yes

Component Information

Component	Substance	CAS Number	Amount (mg)	Homogeneous Material Level		Component Level	
				Percentage %	ppm	Percentage %	ppm
Bond Wire							
Copper and Its Alloys	Copper	7440-50-8	0.376787	99.997346	999973	0.460468	4605
Copper and Its Alloys	Iron	7439-89-6	0.000002	0.000531	5	0.000002	0
Nickel and Its Alloys	Nickel	7440-02-0	0.000001	0.000265	3	0.000001	0
Other Inorganic Materials	Sulfur	7704-34-9	0.000001	0.000265	3	0.000001	0
Other Nonferrous Metals and Alloys	Manganese	7439-96-5	0.000001	0.000265	3	0.000001	0
Precious Metals	Silver	7440-22-4	0.000005	0.001327	13	0.000006	0
Sub-Total			0.376797	100	1000000	0.460481	4605
Die Attach Adhesive							
Precious Metals	Silver	7440-22-4	0.544282	79.999941	799999	0.665163	6652
Thermoplastics	Epoxy	85954-11-6	0.136071	20.000059	200001	0.166291	1663
Sub-Total			0.680353	100	1000000	0.831454	8315
Lead Frame							
Copper and Its Alloys	Copper	7440-50-8	43.49392	97.52	975200	53.153575	531536
Copper and Its Alloys	Iron	7439-89-6	1.0258	2.3	23000	1.253622	12536
Copper and Its Alloys	Phosphorus	7723-14-0	0.01338	0.03	300	0.016352	164
Zinc and Its Alloys	Zinc	7440-66-6	0.0669	0.15	1500	0.081758	818
Sub-Total			44.6	100	1000000	54.505307	545053
Lead Frame Plating							
Nickel and Its Alloys	Nickel	7440-02-0	1.294678	95.119976	951200	1.582216	15822
Precious Metals	Gold	7440-57-5	0.010617	0.780031	7800	0.012975	130
Precious Metals	Palladium	7440-05-3	0.055805	4.099993	41000	0.068199	682
Sub-Total			1.3611	100	1000000	1.66339	16634
Mold Compound							
Other Inorganic Materials	Fused Silica	60676-86-0	28.770088	88	880000	35.159697	351597
Other Organic Materials	Chlorine	7782-50-5	0.000327	0.001	10	0.0004	4
Other Plastics and Rubber	Carbon Black	1333-86-4	0.09808	0.3	3000	0.119863	1199
Thermoplastics	Epoxy	85954-11-6	3.824787	11.699	116990	4.674242	46742
Sub-Total			32.693282	100	1000000	39.954201	399542
Semiconductor Device							
Ceramics / Glass	Doped Silicon	7440-21-3	2.115363	100	1000000	2.585168	25852
Sub-Total			2.115363	100	1000000	2.585168	25852
Total			81.826895			100	1000000

Important Note

The ppm calculations are at the **homogeneous material** level and are maximum concentration values. The ppm displayed represents the **homogeneous material** with the highest ppm for that substance. The amount (mg) calculations represent the maximum total amount of each substance within the component.
 The ppm calculations are at the **component** level and are average concentration values. The amount (mg) calculations represent the average total amount of each substance within the **component**.
[See Glossary of Terms for more details.](#)

Important Part Information

There is a remote possibility the Customer Part Number (CPN) your company uses could reference more than one TI part number. This is due to two or more users (EMSIs or subcontractors) using the same CPN for different TI part numbers. If this occurs, please check your Customer Part Number and cross reference it with the TI part number seen on this page.

Product Content Methodology

[For an explanation of the methods used to determine material weights, See Product Content Methodology](#)

Material Declaration Certificate for Semiconductor IC Packaged Products

TI certifies that the material content information provided by TI is representative and accurate to the best of their knowledge based on material information provided by its suppliers and their combination into finished IC packaged products. TI semiconductor products designated to be "Pb-free", "Green" or "RoHS Exempt" fully meets the latest EU RoHS Directive requirements along with other legislation as seen in the former JIG-101 list that has been transferred to the IEC 62474 database.

Important Information/Disclaimer

TI bases its material content information on information provided by third-party suppliers and has taken, and continues to take, reasonably diligent steps to provide any required or available information. TI may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers may consider certain information to be proprietary, and thus certain information may not be available for release by TI. The material content information is provided by TI "as is."

[For additional information, please contact TI customer support.](#)

[Signature: \(click here for a fuller statement with a signed certificate\)](#)

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 For further environmental statements, please go to www.ti.com/ecoinfo
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RoHS: Means TI semiconductor products that are compliant with the current RoHS requirement that the maximum concentration values of the ten substances listed in RoHS Annex II do not exceed 0.1 % by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI semiconductor products labeled as "RoHS Compliant" are suitable for use in specified lead-free processes. TI may also reference these types of semiconductor products as "Pb-Free." These TI semiconductor products are also fully compliant with GADSL and the IEC 62474 database for electronic requirements.

RoHS Exempt: Means TI semiconductor products that contain lead (Pb) above the RoHS Annex II threshold, but that fall within one of the specific RoHS exemptions noted above or documented in <http://www.ti.com/lit/pdf/szzq088>

Green: Means the content of Chlorine (Cl) and Bromine (Br)-based flame retardants meet JS709B low halogen requirements of <=1 000ppm threshold; Antimony trioxide (Sb2O3) contained in halogen based flame retardant materials meets the <=1 000ppm threshold requirement; and Beryllium Oxide (BeO) is <=1000ppm.